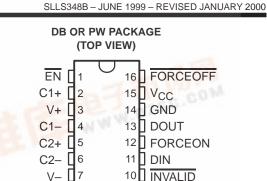
查询MAX3221供应商

捷多邦,专业PCB打样工厂,24小时加急出货 MAX3221 3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER

- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- Operates up to 250 kbit/s
- Low Standby Current . . . 1 µA Typical
- External Capacitors . . . $4 \times 0.1 \ \mu F$
- Accepts 5-V Logic Input With 3.3-V Supply
- Designed to Be Interchangeable With Maxim MAX3221
- **RS-232 Bus-Pin ESD Protection Exceeds** ±15-kV Using Human-Body Model (HBM)
- Applications
 - Battery-Powered Systems, PDAs, Notebooks, Laptops, Palmtop PCs, and Hand-Held Equipment
- **Package Options Include Plastic Shrink** Small-Outline (DB) and Thin Shrink Small-Outline (PW) Packages



8

RIN

9 ROUT

description

The MAX3221 device consists of one line driver, one line receiver, and a dual charge-pump circuit with ±15-kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. These devices operate at data signaling rates up to 250 kbit/s, and at a maximum of 30-V/µs driver output slew rate.

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low and EN is high, both drivers and receivers are shut off, and the supply current is reduced to 1 μA. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output notifies the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μ s. INVALID is low (invalid data) if the receiver input voltage is between -0.3 V and 0.3 V for more than 30 μ s. Refer to Figure 5 for receiver input levels.

The MAX3221C is characterized for operation from 0°C to 70°C. The MAX3221I is characterized for operation from -40°C to 85°C.



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SLLS348B - JUNE 1999 - REVISED JANUARY 2000

	AVAILABLE OPTIONS									
	PACKAGED DEVICES									
TA	SHRINK SMALL OUTLINE (DB)	THIN SHRINK SMALL OUTLINE (PW)								
0°C to 70°C	MAX3221CDB	MAX3221CPW								
-40°C to 85°C	MAX3221IDB	MAX3221IPW								

The DB and PW packages are available taped and reeled. Add the suffix R to device type (e.g., MAX3221CDBR).

Function Tables

EACH DRIVER

		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Х	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
н	Н	Н	Х	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
н	L	Н	No	Z	auto-powerdown feature

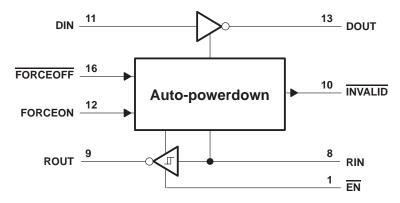
H = high level, L = low level, X = irrelevant, Z = high impedance

EACH RECEIVER

	INPUTS				
RIN	EN	VALID RIN RS-232 LEVEL	OUTPUT ROUT		
L	L	Х	Н		
н	L	Х	L		
Х	Н	Х	Z		
Open	L	No	Н		

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = disconnected input or connected driver off

logic diagram (positive logic)





SLLS348B - JUNE 1999 - REVISED JANUARY 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

$\begin{array}{llllllllllllllllllllllllllllllllllll$	$\begin{array}{c}0.3 \ V \ to \ 7 \ V \\ 0.3 \ V \ to \ -7 \ V \\ 13 \ V \\0.3 \ V \ to \ 6 \ V \\25 \ V \ to \ 25 \ V \\ 13.2 \ V \ to \ 13.2 \ V \\ 13.2 \ V \ to \ 13.2 \ V \\ 82^{\circ} C/W \\ 108^{\circ} C/W \\ 260^{\circ} C \end{array}$
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† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3 and Figure 6)

						MAX	UNIT
	Supply voltage		$V_{CC} = 3.3 V$	3	3.3	3.6	V
			$V_{CC} = 5 V$	4.5	5	5.5	v
V	VIH Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON,	V _{CC} = 3.3 V	2			V
VIH	Driver and control high-level input voltage	EN	$V_{CC} = 5 V$	2.4			v
VIL	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON, EN				0.8	V
VI	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
VI	V _I Receiver input voltage			-25		25	V
ТА	Operating free-air temperature			0		70	°C
	Operating nee-an temperature		MAX3221I	-40		85	C

NOTE 3: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP‡	MAX	UNIT	
Ц	Input leakage current	FORCEOFF, FORCEON, EN			±0.01	±1	μΑ
		Auto-powerdown disabled	No load, FORCEOFF and FORCEON at V_{CC}		0.3	1	mA
ICC	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
		Auto-powerdown enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

[‡] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C. NOTE 3: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.





SLLS348B - JUNE 1999 - REVISED JANUARY 2000

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST C	ONDITIONS		MIN	TYP [†]	MAX	UNIT
VOH	High-level output voltage	DOUT at $R_L = 3 k\Omega$ to GND,	DIN = GND		5	5.4		V
VOL	Low-level output voltage	DOUT at $R_L = 3 k\Omega$ to GND,	$DIN = V_{CC}$		-5	-5.4		V
Чн	High-level input current	$A^{I} = A^{CC}$				±0.01	±1	μΑ
۱ _{IL}	Low-level input current	V _I at GND				±0.01	±1	μΑ
100		V _{CC} = 3.6 V,	$V_{O} = 0 V$			±35	±60	mA
los	Short-circuit output current‡	V _{CC} = 5.5 V,	VO = 0 V			±35	±00	ША
r _o	Output resistance	V_{CC} , V+, and V- = 0 V,	$V_{O} = \pm 2 V$		300	10M		Ω
loff	Output leakage current	FORCEOFF = GND,	V _O = ±12 V,	V_{CC} = 0 to 5.5 V			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3$ V or $V_{CC} = 5$ V, and $T_A = 25^{\circ}$ C.

[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

NOTE 3: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
	Maximum data rate	C _L = 1000 pF,	$R_L = 3 k\Omega$,	See Figure 1	250			kbit/s
^t sk(p)	Pulse skew§	C _L = 150 pF to 2500 pF	$R_L = 3 k\Omega$ to See Figure 2		100		ns	
SD(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	C _L = 150 pF	to 1000 pF	6		30	V/µs
SR(tr)	(see Figure 1)	$R_L = 3 k\Omega$ to 7 k Ω	C _L = 150 pF	to 2500 pF	4		30	v/µS

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

§ Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

NOTE 3: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



SLLS348B - JUNE 1999 - REVISED JANUARY 2000

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
VOH	High-level output voltage	I _{OH} = -1 mA	V _{CC} – 0.6 V	$V_{CC} - 0.1 V$		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
	Positive-going input threshold voltage	V _{CC} = 3.3 V		1.6	2.4	V
VIT+	Positive-going input theshold voltage	$V_{CC} = 5 V$		1.9	2.4	v
V	Negative-going input threshold voltage	V _{CC} = 3.3 V	0.6	1.1		V
V _{IT} –	Negative-going input the shout voltage	$V_{CC} = 5 V$	0.8	1.4		v
V _{hys}	Input hysteresis (V _{IT+} – V _{IT} –)			0.5		V
loff	Output leakage current	FORCEOFF = 0 V		±0.05	±10	μΑ
rj	Input resistance	$V_I = \pm 3 V$ to $\pm 25 V$	3	5	7	kΩ

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 3: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 3)

	PARAMETER	TEST CONDITIONS	MIN TYP [†] M	AX UNIT
^t PLH	Propagation delay time, low- to high-level output	C _I = 150 pF, See Figure 3	150	ns
^t PHL	Propagation delay time, high- to low-level output	CL = 150 pr, See Figure 5	150	ns
t _{en}	Output enable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega$, See Figure 4	200	ns
^t dis	Output disable time	$C_{L} = 150 \text{ pr}, \text{ K}_{L} = 3 \text{ K}_{2}, \text{ See Figure 4}$	200	ns
t _{sk(p)}	Pulse skew [‡]	See Figure 3	50	ns

[†] All typical values are at $V_{CC} = 3.3$ V or $V_{CC} = 5$ V, and $T_A = 25^{\circ}$ C.

[‡] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

NOTE 3: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



SLLS348B - JUNE 1999 - REVISED JANUARY 2000

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{T+(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}			2.7	V
VT-(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7			V
VT(invalid)	Receiver input threshold for (INVALID) low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3		0.3	V
V _{OH}	INVALID high-level output voltage	$I_{OH} = -1 \text{ mA}$, FORCEON = GND, FORCEOFF = V _{CC}	V _{CC} – 0.6			V
VOL	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}$, FORCEON = GND, FORCEOFF = V_{CC}			0.4	V

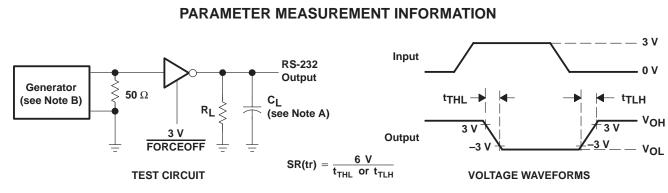
[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	MIN TYP	MAX	UNIT
^t valid	Propagation delay time, low- to high-level output	1		μs
^t invalid	Propagation delay time, high- to low-level output	30		μs
ten	Supply enable time	100		μs

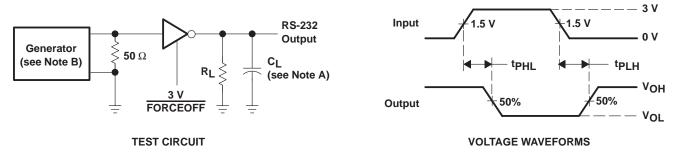
[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

SLLS348B - JUNE 1999 - REVISED JANUARY 2000



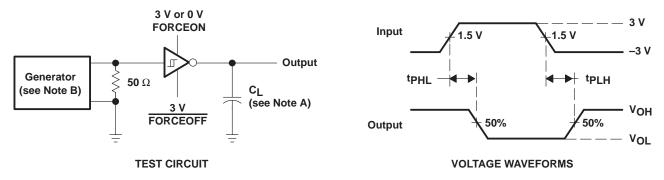
NOTES: A. C_L includes probe and jig capacitance. B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 1. Driver Slew Rate



NOTES: A. CL includes probe and jig capacitance. B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_0 = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 2. Driver Pulse Skew



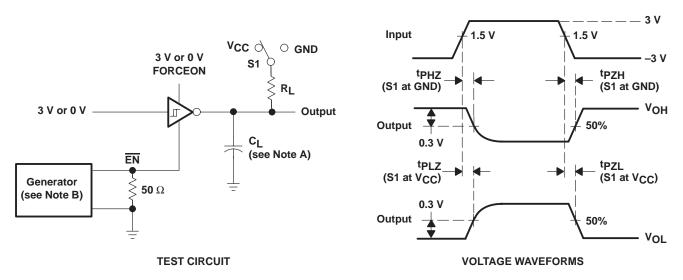
NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times



SLLS348B – JUNE 1999 – REVISED JANUARY 2000



PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

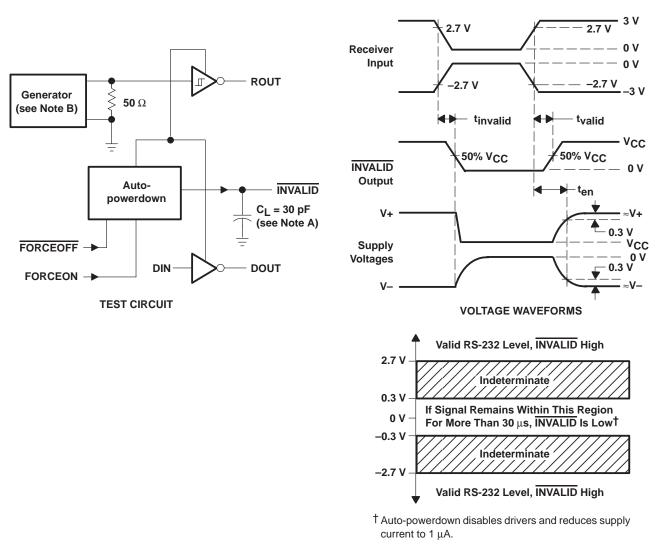
B. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

- C. tpLz and tpHz are the same as tdis.
- D. tpzL and tpzH are the same as ten.

Figure 4. Receiver Enable and Disable Times



SLLS348B - JUNE 1999 - REVISED JANUARY 2000



PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

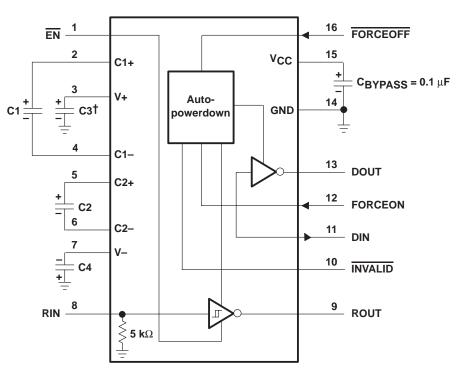
B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Driver Enabling Time





SLLS348B - JUNE 1999 - REVISED JANUARY 2000



APPLICATION INFORMATION

 † C3 can be connected to V_{CC} or GND.

NOTE A: Resistor values shown are nominal.

V_{CC} vs CAPACITOR VALUES

VCC	C1	C2, C3, and C4
$\begin{array}{c} \textbf{3.3 V} \pm \textbf{0.3 V} \\ \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{3 V to 5.5 V} \end{array}$	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF

Figure 6. Typical Operating Circuit and Capacitor Values



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